



Contact EoPlex

1321 Ridder Park Drive, Suite 10
 San Jose, CA 95131
 408.638.5100
 info@eoplex.com

CSI™ Power

Preliminary Product Brief

Overview

The CSI™ Power is the ideal solution for digital and analog power devices, and mechanical stress sensitive MEMS applications. Significant thermal improvements are achieved through the removal of the center die attach pad. This results in excellent heat dissipation and puts less stress on the die from varying thermal expansion coefficients.

The below data is for reference only. For detailed analysis on specific packages, contact EoPlex at info@eoplex.com.

Thermal Performance, Component Level

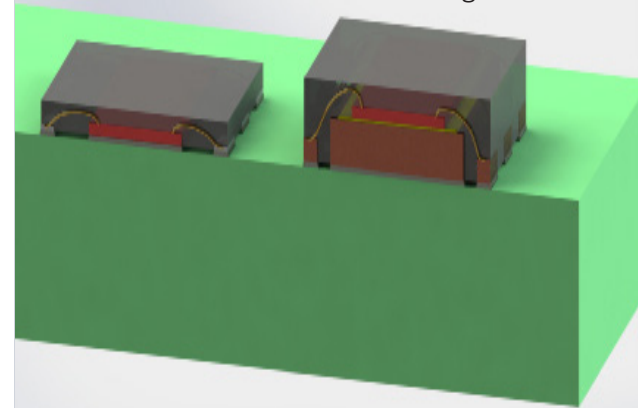
Lead Count	Package Size (mm)	θJA (°C/W)		
		0 m/s	1 m/s	2 m/s
16	3 x 3	48.83	46.91	44.99
40	6 x 6	21.47	19.54	17.63
132	10 x 10	16.44	14.50	12.59
224	12 x 12	15.39	13.47	11.56

Electrical Performance

Lead Count	Package Size (mm)	Ls(nH)	Lm(nH)	C(pf)	Cm(pf)
16	3 x 3	0.51	0.24	0.11	0.03
40	6 x 6	1.10	0.42	0.18	0.04
132	10 x 10	1.45	0.71	0.22	0.06
224	12 x 12	1.60	0.82	0.24	0.06

Package with CSI™ Power

Traditional Package



Highlights

- No Center Die Attach Pad
- Printed Components
- Multi-Row I/O
- Thin package, 0.25 mm
- Custom Design Flexibility
- Green Process
- Compatible with SiP

Specifications

- Wire Bond: Gold or Copper
- Lead Finish: Sintered Silver
- Bond Pad Pitch: > 0.2mm

Application Areas

- Analog Power Devices
- Digital Power Devices
- MEMS (Select Classes)
- Sensors